

PCN Number:	20221201001.1		PCN Date:	December 09, 2022												
Title:	Qualification of TI CDAT as Additional Assembly Site for Select QFN Package Device															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	Mar 09, 2023	Sample requests accepted until:	Jan 09, 2023*													
*Sample requests received after (Jan 09, 2023) will not be supported.																
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
				<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
Texas Instruments Incorporated is announcing the qualification TI CDAT as Additional Assembly Site for select device listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>TI Clark</td> <td>QAB</td> <td>PHL</td> <td>Angeles City, Pampanga</td> </tr> <tr> <td>TI CDAT</td> <td>CDA</td> <td>CHN</td> <td>Chengdu</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	TI Clark	QAB	PHL	Angeles City, Pampanga	TI CDAT	CDA	CHN	Chengdu
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City													
TI Clark	QAB	PHL	Angeles City, Pampanga													
TI CDAT	CDA	CHN	Chengdu													
Material Differences:																
	TI Clark	TI CDAT														
Mold Compound	4222790	4223495														
Lead finish	NiPdAu	Matte Sn														
Upon expiration of this PCN, TI will combine lead free solutions in a single <i>standard part number</i> , for example; <i>SN2004053RWUR</i> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. <i>SN2004053RWURG4.</i> "																
Reason for Change:																
Continuity of supply.																
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																
None																
Impact on Environmental Ratings:																
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																
	RoHS	REACH	Green Status	IEC 62474												
<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>												
Changes to product identification resulting from this PCN:																

Assembly Site		
TI Clark	Assembly Site Origin (22L)	ASO: QAB
TI-CDAT	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SN2004053RWUR	TPS61022RWUT
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Qualification Report

Approve Date 28-Nov-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN2004053RWUR	Product QBS Reference: TPS61022RWUR	Product QBS Reference: TPS61022RWUR	Package QBS Reference: TPS51393RJR	Package QBS Reference: TPS543620RPYR
HAST	A2	Biased HAST	130C/85% RH	96 Hours	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85% RH	96 Hours	-	1/77/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/230/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	1/800/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;	-	-	-	-	3/66/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/66/0	3/66/0

PD	C 4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	3/15/0
ESD	E 2	ESD CDM	-	1000 Volts	-	-	3/9/0	-	-
ESD	E 2	ESD HBM	-	3000 Volts	-	-	3/9/0	3/9/0	-
LU	E 4	Latch-Up	Per JESD78	-	-	-	3/18/0	3/18/0	-
CHAR	E 5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	3/90/0	-

QBS: Qual By Similarity

Qual Device SN2004053RWUR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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